

PRODUCT SPECIFICATION

Part Number
PLBT3535R-WCNW

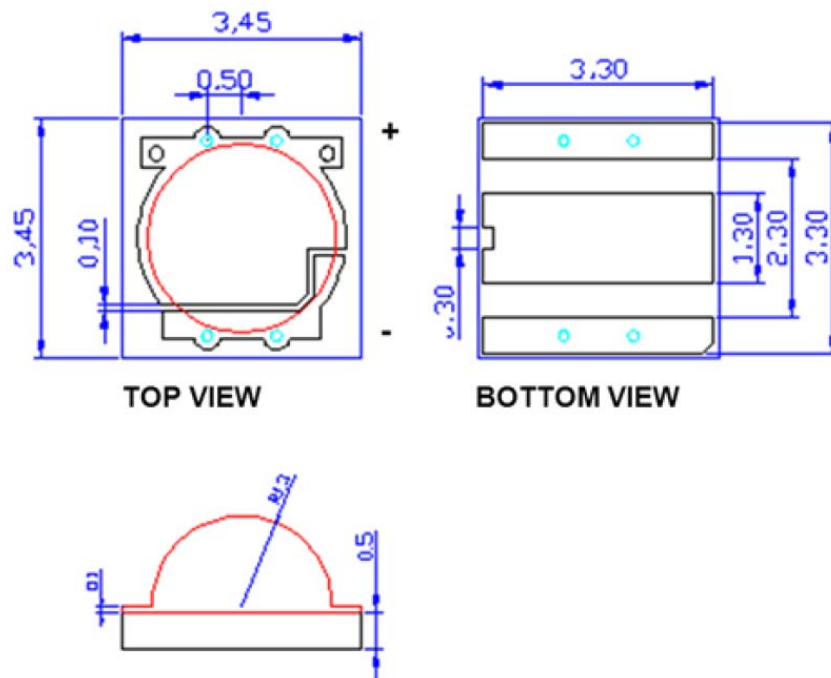
Details

- Round Lens SMD
- 130° viewing angle.
- Emitting Color: Natural White
- InGaN dice used

Features

- Qualified according to JEDEC moisture sensitivity level 2A
- RoHS Compliant
- Easy mounting on PCB

Mechanical Dimensions



Notes:

1. Dimension in millimeter [inch], and tolerance is ± 0.13 mm unless otherwise noted.
2. Specifications subject to change without notice



Device Selection Guide

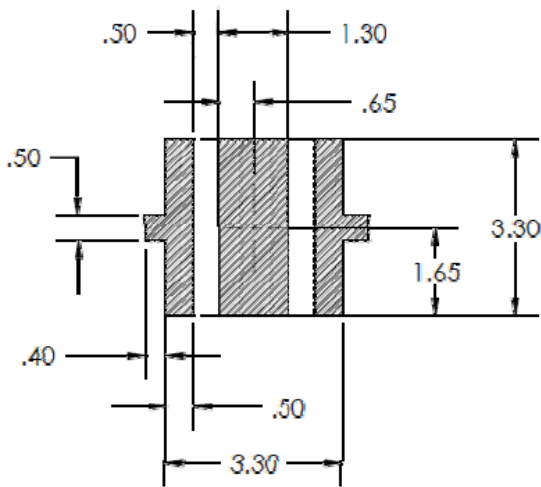
Model Number	Chip	
PLBT3535R-WCNW	Material	Emitting Color
	InGaN	Natural White

Absolute Maximum Ratings at Ta=25°C

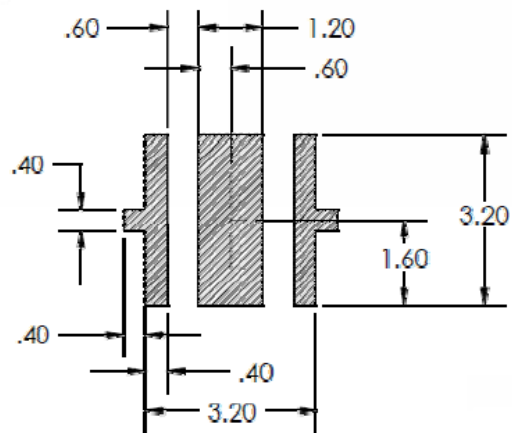
Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	1-3	W
Continuous Forward Current	I _{AF}	700	mA
Reverse Voltage	V _r	5	V
Operating Temperature	T _{opr}	-30~+85	°C
Storage Temperature	T _{stg}	-40~+100	°C

Electrical and Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V _F	--	3.0	--	V	IF=350mA
Luminous Flux	Φ _v	120	130		Lm	IF=350mA
Chromacity Coordinates	X	--	0.375		nm	IF=350mA
	Y	--	0.365		nm	IF=350mA
Reverse Current	I _R	--	--	10	μA	VR=5V
Color Temperature	CCT	--	4000	--	°K	IF=350mA

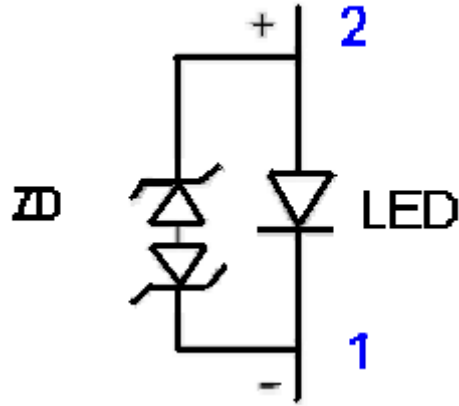


RECOMMENDED PCB SOLDER PAD



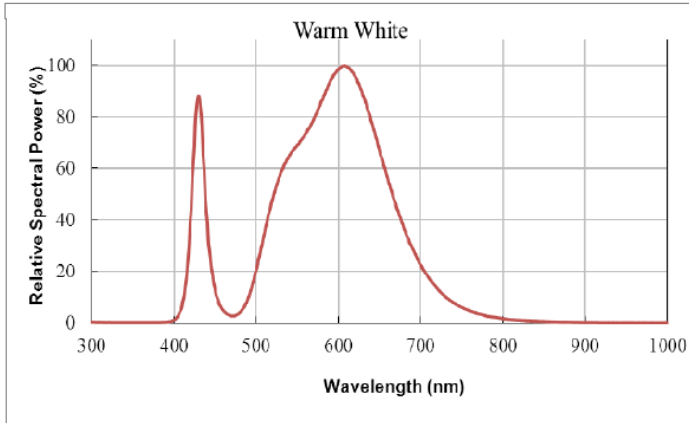
**RECOMMENDED STENCIL PATTERN
(HATCHED AREA IS OPENING)**

Internal Circuit Diagram

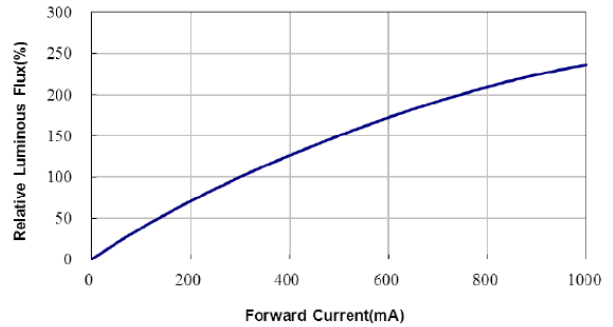


Typical Electrical / Optical Characteristic Curves

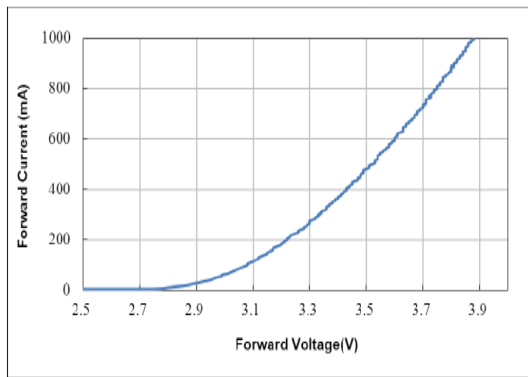
Relative Radiant Power VS Wavelength @Ta=25°C



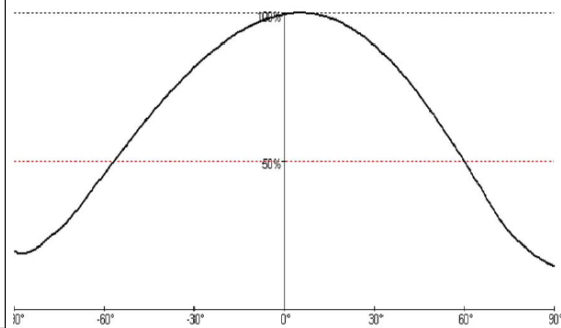
Relative Luminous Flux VS Forward Current @Ta=25°C



Forward Current VS Forward Voltage @Ta=25°C

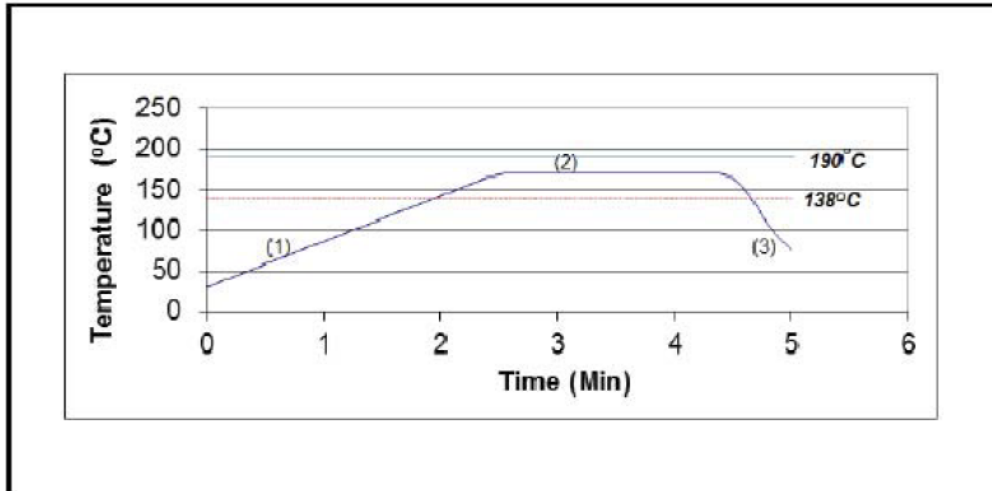


White Color Radiation Angle



IR Reflow Temperature / Time

Lead Free solder



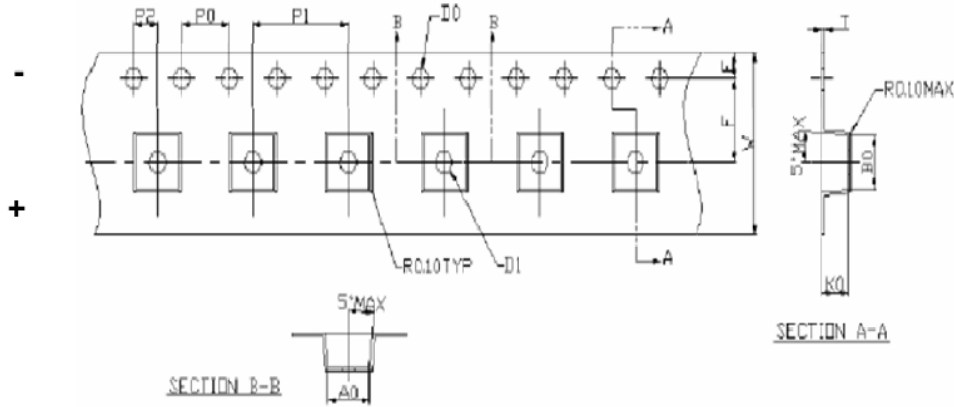
Profile Feature	Eutectic Assembly
(1) Preheat	0.5~1.0°C/second. 120~150 seconds
(2) Soak and reflow	170~190°C. 90-120 seconds
(3) Cooling stage	-3~-4 °C/ second. 30-60 seconds

Notes:

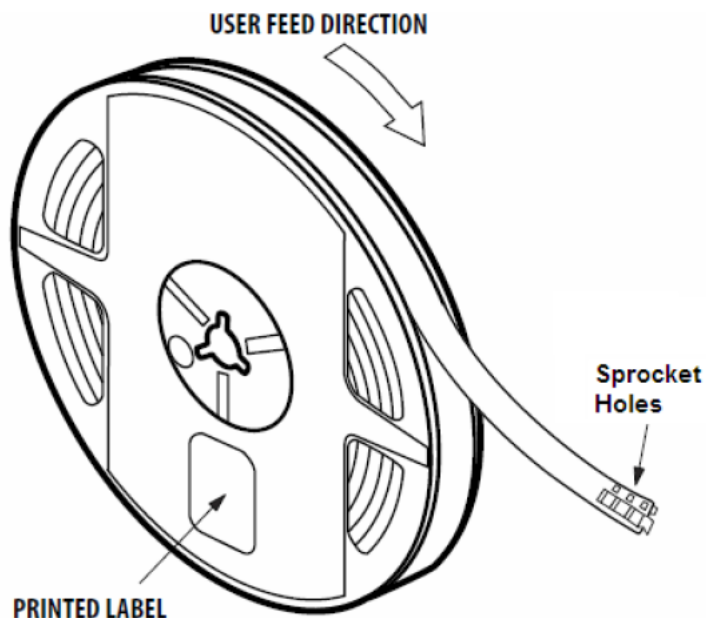
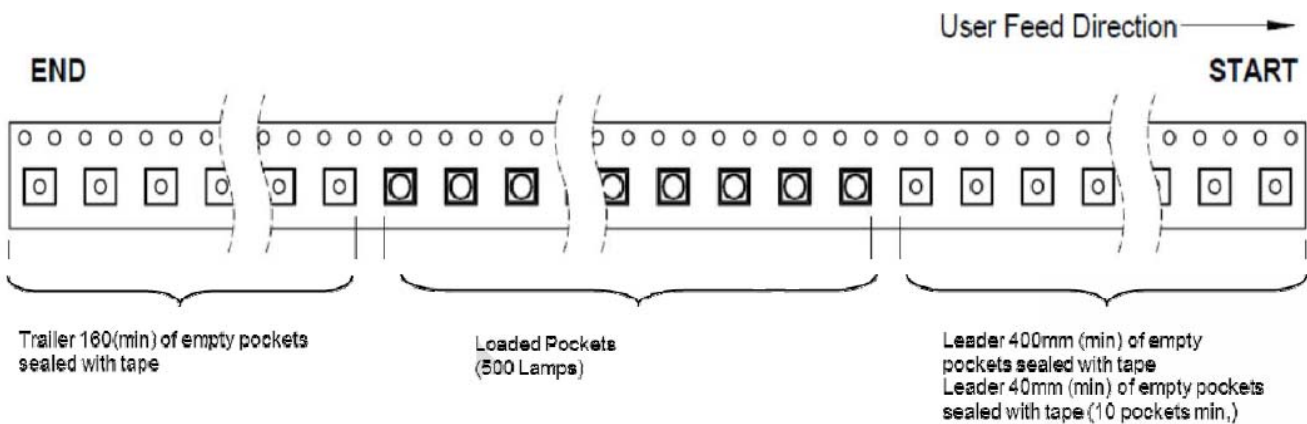
1. We recommend reflow temp of 180°C (+/- 5°C) Maximum soldering temp should be limited to 190°C
2. Do not cause stress to the epoxy resin while it is exposed to high temperature
3. Number of reflow process shall be 1 time

Tape and Reel Dimensions

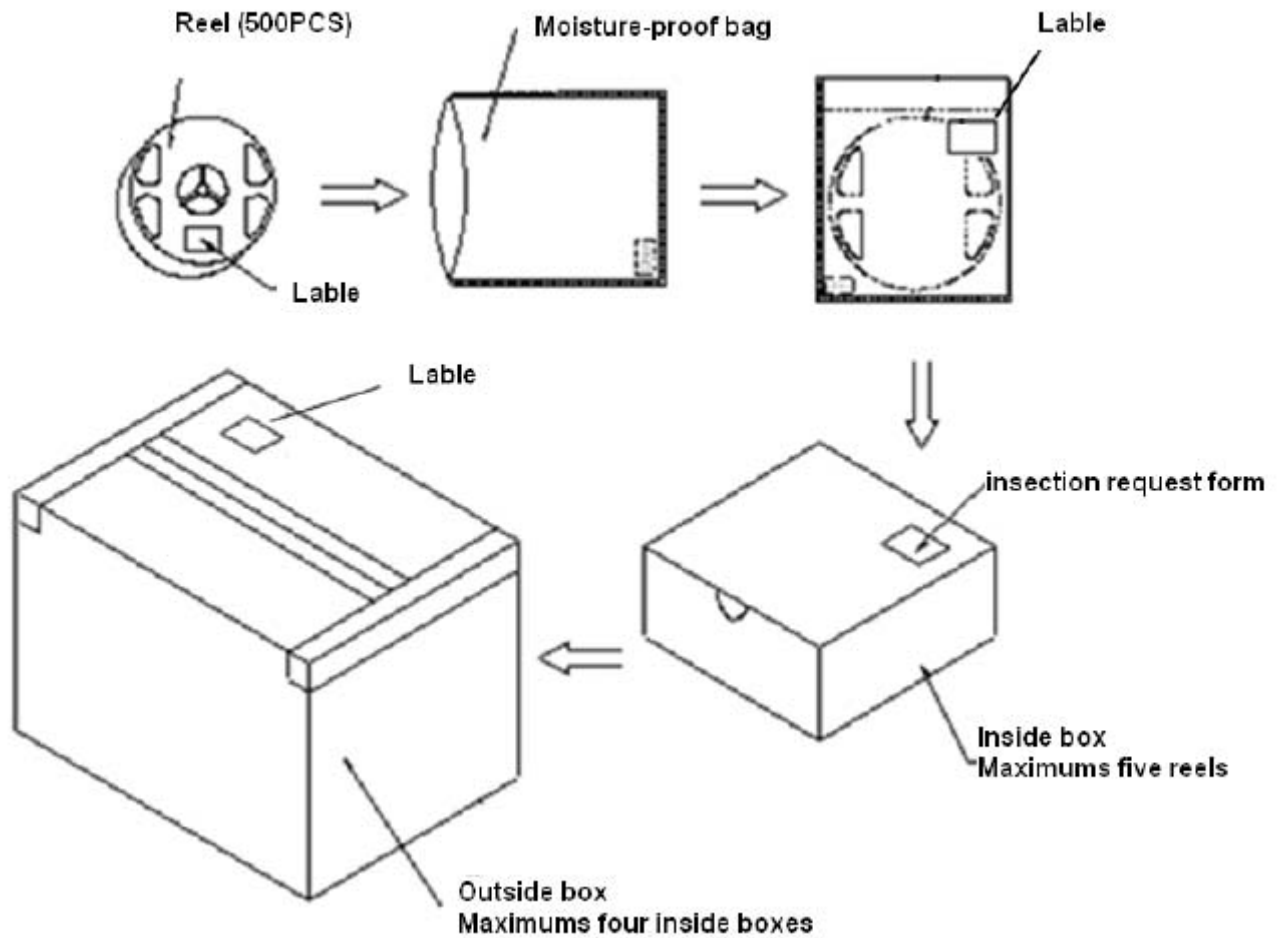
■ Tape and Reel



Item	Specification	Tol.(+/-)
W	12.00	±0.30
E	1.75	±0.10
F	5.50	±0.10
D0	1.50	+0.1 -0
D1	1.50	±0.10
P0	4.00	±0.10
P1	8.00	±0.10
P2	2.00	±0.10
P0 x 10	40.00	±0.20
t	0.30	±0.05
A0	3.67	±0.10
B0	3.60	±0.10
K0	2.20	±0.10



Packing and Label Specifications





Note:

1. Specifications subject to change without notice.